TOSHIBA

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RD Number: RD081

RD Title: TB6642FG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	IC1	1	TB6642FG	TB6642FG	TOSHIBA	Motor driver IC		
2	OUT1	1	Check terminal	—	_	Check terminal for logic		
3	R1	0	Not mount	—	_	Leaded resistor		√
4	C3	0	Not mount	—	_	Leaded capacitor		\checkmark
5	CON	1	Connector	—	_	CONN HEADER VERT 2POS		
6	RSGND	1	Check terminal	—	_	Check terminal for oscilloscope		
7	R2	1	0Ω	—	_	Chip resistor	5.0mm×2.5mm	
8	OUT2	1	Check terminal	—	—	Check terminal for logic		
9	VM	1	Check terminal	—	_	Check terminal for logic		
10	C1	1	100µF 50V	—	-	Electrolytic capacitor		
11	C2	1	0.1µF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
12	VISD/VREG	0	Check terminal	—	_	Check terminal for oscilloscope		√
13	R4/C5	0	10kΩ 0.25W	—	-	Chip resistor	3.2mm×1.6mm	√
14	R4/C5	1	10kΩ 0.25W	—	-	Leaded resistor		
15	R4/C5	0	0.1µF 25V	—	_	Chip capacitor	3.2mm×1.6mm	√
16	R4/C5	0	0.1µF 25V	—	_	Leaded capacitor		√
17	JP_VREG	0	Pin header 2P	—	_	Single row plugs		\checkmark
18	JP_VREG	0	Jump socket	—	-	Position Shunt Connector		√
19	TISD	0	Check terminal	—	_	Check terminal for oscilloscope		√
20	R3	0	5kΩ 0.25W	—	-	Chip resistor	3.2mm×1.6mm	√
21	R3	1	5kΩ 0.25W	—	-	Leaded resistor		
22	PWM	0	Check terminal	—	_	Check terminal for oscilloscope		√
23	SW_PWM	0	Toggle Switch	—	_	SPDT Toggle Switch		√
24	SW_PWM	1	Pin header 3P	-	_	Single row plugs		
25	SW_PWM	1	Jump socket	-	_	Position Shunt Connector		

26 VREF	0	Check terminal	—	_	Check terminal for logic		\checkmark
27 JP_VREF	1	Pin header 2P	—	-	Single row plugs		
28 JP_VREF	1	Jump socket	—	-	Position Shunt Connector		
29 R6	0	Not mount	—	—	Chip resistor	3.2mm×1.6mm	√
30 R6	0	Not mount	—	—	Leaded resistor		√
31 R7	0	Not mount	—	-	Chip resistor	3.2mm×1.6mm	√
32 R7	0	Not mount	—	—	Leaded resistor		√
33 ALERT	1	Check terminal	—	—	Check terminal for oscilloscope		
34 R5	1	100kΩ 0.25W	—	-	Leaded resistor		
35 C4/R8(OSC)	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	√
36 C4/R8(OSC)	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
37 IN1	1	Check terminal	—	-	Check terminal for oscilloscope		
38 SW_IN1	0	Toggle Switch	—	—	SPDT Toggle Switch		~
39 SW_IN1	1	Pin header 3P	—	—	Single row plugs		
40 SW_IN1	1	Jump socket	—	—	Position Shunt Connector		
41 GND(SGND)	5	Check terminal	—	-	Check terminal for logic		
42 IN2	1	Check terminal	—	—	Check terminal for oscilloscope		
43 SW_IN2	0	Toggle Switch	—	—	SPDT Toggle Switch		√
44 SW_IN2	1	Pin header 3P	—	—	Single row plugs		
45 SW_IN2	1	Jump socket	—	—	Position Shunt Connector		
46 VDD	1	Check terminal	—	—	Check terminal for logic		
47 C6	0	10µF 25V		_	Electrolytic capacitor		√
48 C7	1	0.1µF 25V	—	—	Chip capacitor	3.2mm×1.6mm	

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